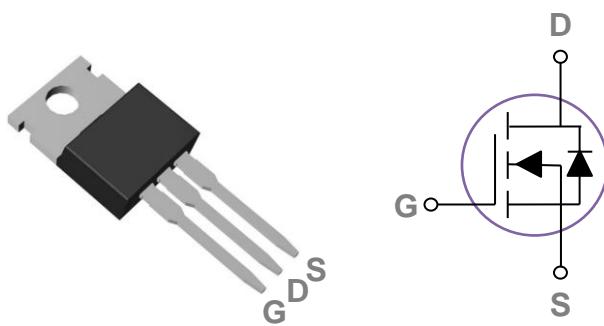


### General Description

These N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

### TO220 Pin Configuration



BVDSS	RDS(ON)	ID
65V	5.9mΩ	85A

### Features

- 65V,85A,  $RDS(ON) = 5.9m\Omega @ VGS = 10V$
- Improved dv/dt capability
- Fast switching
- 100% EAS Guaranteed
- Green Device Available

### Applications

- Networking
- Load Switch
- LED applications
- Quick Charger

### Absolute Maximum Ratings $T_c=25^\circ C$ unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	65	V
$V_{GS}$	Gate-Source Voltage	+20/-12	V
$I_D$	Drain Current – Continuous ( $T_c=25^\circ C$ )	85	A
	Drain Current – Continuous ( $T_c=100^\circ C$ )	54	A
$I_{DM}$	Drain Current – Pulsed <sup>1</sup>	340	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	140	mJ
IAS	Single Pulse Avalanche Current <sup>2</sup>	53	A
$P_D$	Power Dissipation ( $T_c=25^\circ C$ )	122	W
	Power Dissipation – Derate above 25°C	0.98	W/°C
$T_{STG}$	Storage Temperature Range	-55 to 150	°C
$T_J$	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to ambient	---	62	°C/W
$R_{\theta JC}$	Thermal Resistance Junction to Case	---	1.02	°C/W

**Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)**
**Off Characteristics**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$\text{BV}_{\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$ , $I_D=250\mu\text{A}$	65	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	$\text{BV}_{\text{DSS}}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=1\text{mA}$	---	0.03	---	$\text{V}/^\circ\text{C}$
$I_{\text{DS}}^{\text{SS}}$	Drain-Source Leakage Current	$V_{\text{DS}}=60\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=25^\circ\text{C}$	---	---	1	$\mu\text{A}$
		$V_{\text{DS}}=48\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $T_J=85^\circ\text{C}$	---	---	10	$\mu\text{A}$
$I_{\text{GSS}}$	Gate-Source Leakage Current	$V_{\text{GS}}=20\text{V}$ , $V_{\text{DS}}=0\text{V}$	---	---	100	$\text{nA}$

**On Characteristics**

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=10\text{V}$ , $I_D=20\text{A}$	---	5	5.9	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}$ , $I_D=15\text{A}$	---	8.9	11.2	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$ , $I_D = 250\mu\text{A}$	1	1.6	2.5	V
			---	-5.5	---	$\text{mV}/^\circ\text{C}$
$g_{\text{fs}}$	Forward Transconductance	$V_{\text{DS}}=10\text{V}$ , $I_D=3\text{A}$	---	10	---	S

**Dynamic and switching Characteristics**

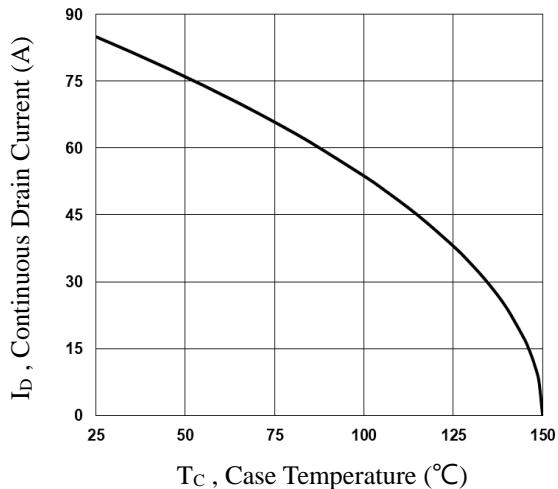
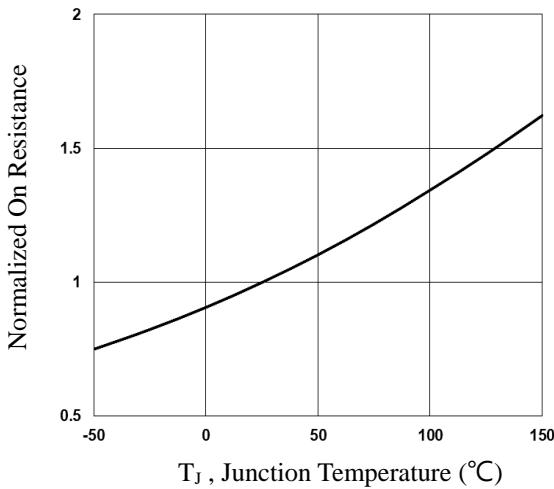
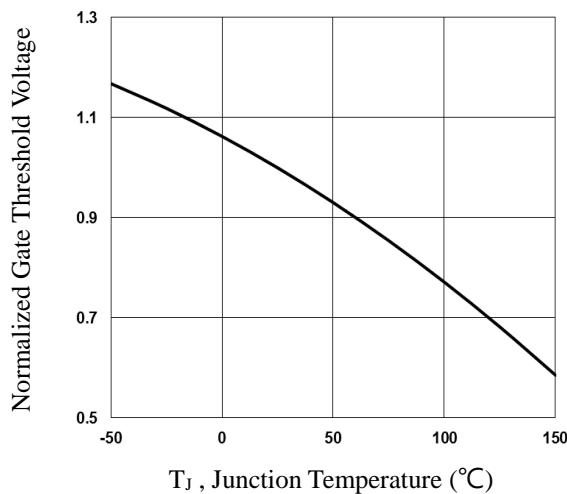
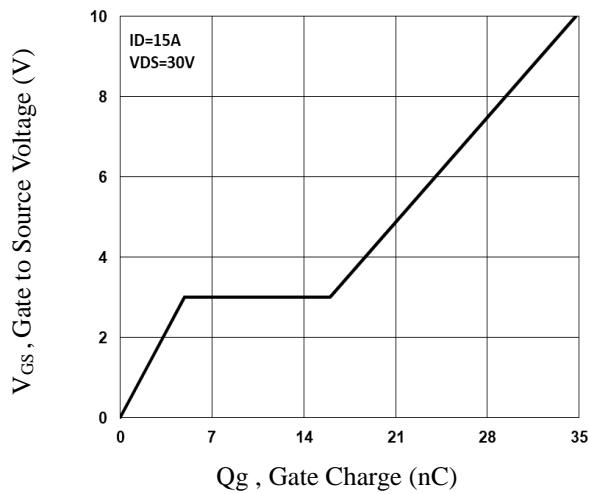
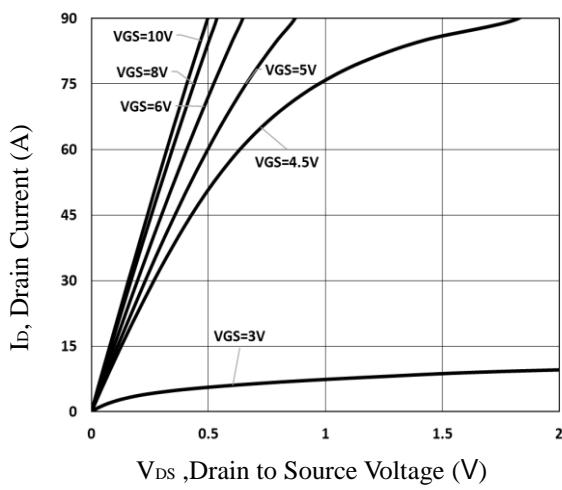
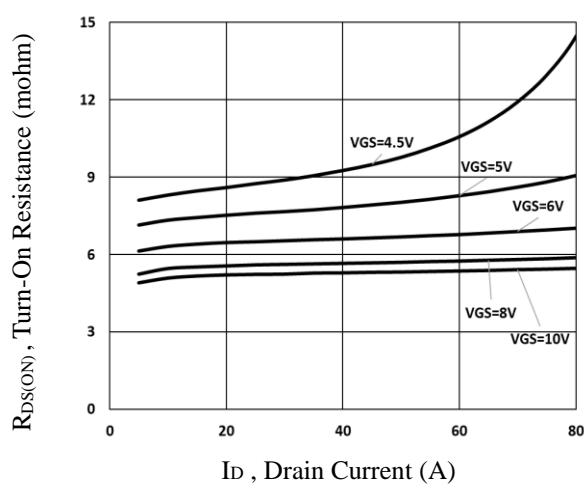
$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $I_D=15\text{A}$	---	34.7	70	nC
$Q_{\text{gs}}$	Gate-Source Charge <sup>3, 4</sup>		---	4.9	10	
$Q_{\text{gd}}$	Gate-Drain Charge <sup>3, 4</sup>		---	11.1	22	
$T_{\text{d(on)}}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{\text{DD}}=30\text{V}$ , $V_{\text{GS}}=10\text{V}$ , $R_G=6\Omega$	---	10.2	21	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	16	32	
$T_{\text{d(off)}}$	Turn-Off Delay Time <sup>3, 4</sup>		---	42	84	
$T_f$	Fall Time <sup>3, 4</sup>		---	38	76	
$C_{\text{iss}}$	Input Capacitance	$V_{\text{DS}}=30\text{V}$ , $V_{\text{GS}}=0\text{V}$ , $F=1\text{MHz}$	---	1910	3800	pF
$C_{\text{oss}}$	Output Capacitance		---	520	1040	
$C_{\text{rss}}$	Reverse Transfer Capacitance		---	30	60	
$R_g$	Gate resistance	$V_{\text{GS}}=0\text{V}$ , $V_{\text{DS}}=0\text{V}$ , $F=1\text{MHz}$	---	1.2	---	$\Omega$

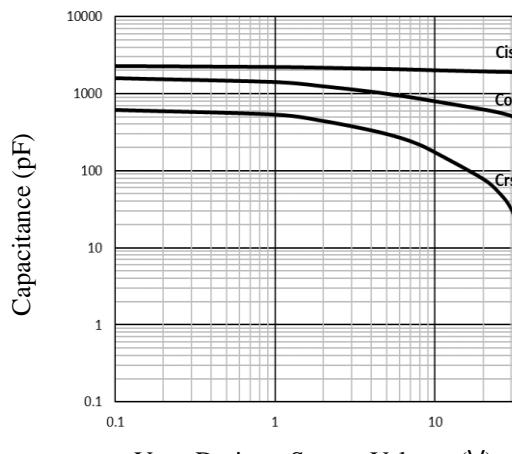
**Drain-Source Diode Characteristics and Maximum Ratings**

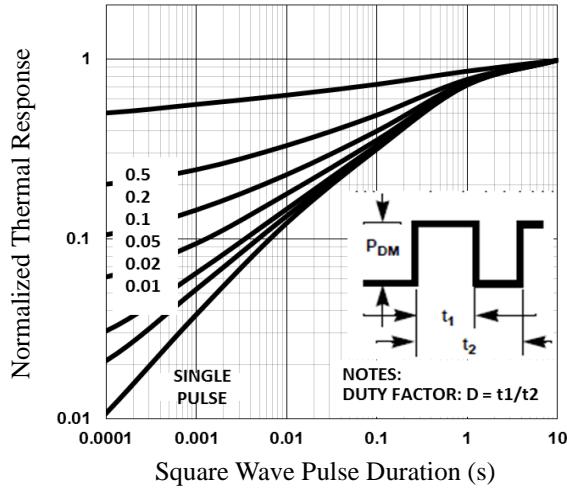
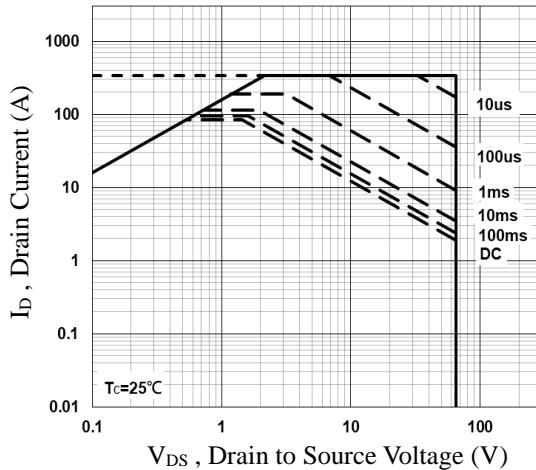
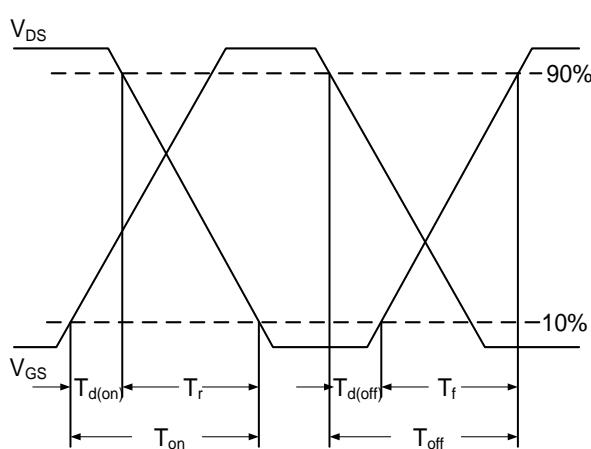
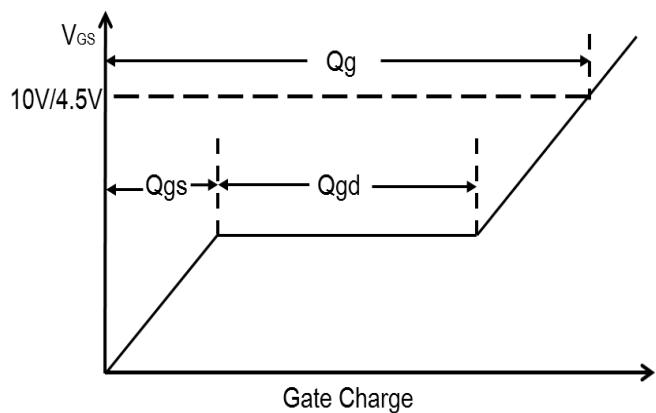
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_s$	Continuous Source Current	$V_G=V_D=0\text{V}$ , Force Current	---	---	85	A
			---	---	170	A
$V_{\text{SD}}$	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$ , $I_s=1\text{A}$ , $T_J=25^\circ\text{C}$	---	---	1	V
			---	48.4	---	ns
$Q_{\text{rr}}$	Reverse Recovery Charge	$T_J=25^\circ\text{C}$	---	54.2	---	nC

Note :

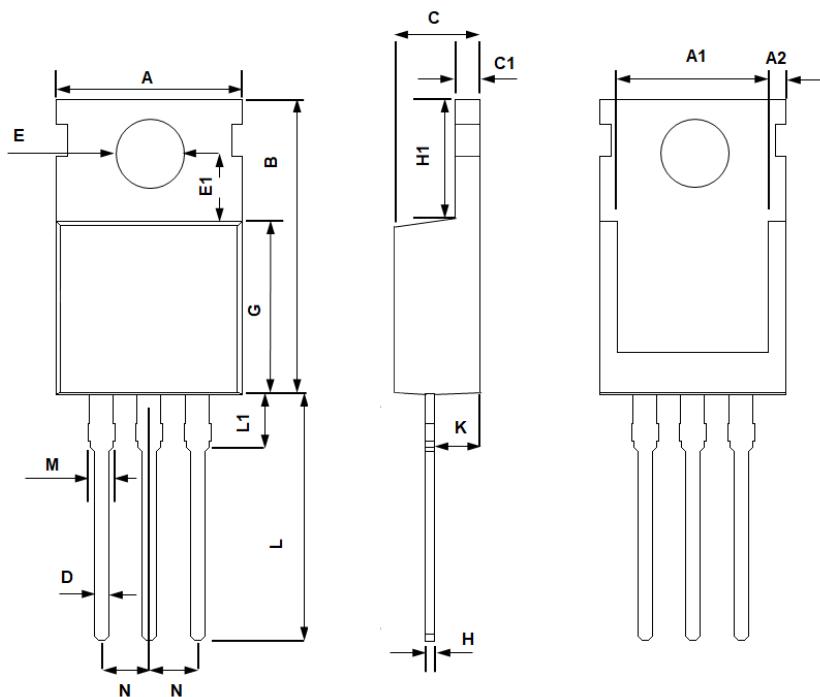
1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{\text{DD}}=25\text{V}$ ,  $V_{\text{GS}}=10\text{V}$ ,  $L=0.1\text{mH}$ ,  $I_{\text{AS}}=53\text{A}$ ,  $R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed , pulse width  $\leq 300\mu\text{s}$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.


**Fig.1 Continuous Drain Current vs. Tc**

**Fig.2 Normalized RDSON vs. Tj**

**Fig.3 Normalized Vth vs. Tj**

**Fig.4 Gate Charge Characteristics**

**Fig.5 Typical Output Characteristics**

**Fig.6 Turn-On Resistance vs. Id**


 V<sub>DS</sub>, Drain to Source Voltage (V)

**Fig.7 Capacitance Characteristics**

**Fig.8 Normalized Transient Impedance**

**Fig.9 Maximum Safe Operation Area**

**Fig.10 Switching Time Waveform**

**Fig.11 Gate Charge Waveform**

## TO220 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	10.400	9.700	0.409	0.382
A1	8.900	7.400	0.350	0.291
A2	1.400	0.800	0.055	0.031
B	16.500	14.500	0.650	0.571
C	4.750	4.200	0.187	0.165
C1	1.500	1.100	0.059	0.043
D	1.000	0.600	0.039	0.024
E	4.000	3.300	0.157	0.130
E1	3.800	3.400	0.150	0.134
G	9.400	8.400	0.370	0.331
H	0.600	0.200	0.024	0.008
H1	6.850	6.200	0.270	0.244
K	2.850	2.100	0.112	0.083
L	14.000	12.500	0.551	0.492
L1	4.000	2.700	0.157	0.106
M	1.750	1.100	0.069	0.043
N	2.640	2.440	0.104	0.096